

**In the Specification:**

Page 1, after the title, add the following paragraph:

This application is claims priority under 35 U.S.C. § 119 based upon provisional application Serial No. 60/258,525, filed December 28, 2000.

Page 5, lines 14 to 25, amend the paragraph to read as follows:

In two recent U.S. Patent Applications, Serial No. 09/737,710 # 60/172,186, filed 12/17/1999 (Rolda et al., "Multi-Flip-Chip Semiconductor Assembly"), now abandoned, and Serial No. 09/992,387 # 60/249,385, filed 11/ 16/2000 (Coyle et al., "Flip-Chip on Film Assembly for Ball Grid Array Packages"), to which the present invention is related, flip-chip assembly techniques have been described for typical pitch using solder balls to fine pitch using gold bumps. These approaches, however, are still too expensive in product assembly as well as cost-of-ownership. Cost has recently become the dominant driving force in the semiconductor marketplace, especially for products using chip-scale devices.